

## Product Change Notice (PCN)

**Subject:** Site addition of Wafer Process for ATJ-Kumamoto products of RH850/F1L series.

**Publication Date:** 9/28/2023

**Effective Date:** 1/8/2024

**Revision Description:** Revision 1 (Correction of typos)

**Description of Change:**

Renesas plans to add the sites of Wafer Process and Wafer Test: Naka for ATJ-Kumamoto products of RH850/F1L series. Please refer to the following for details.

Items		Before change	After change
Production sites	Wafer Process	TSMC	TSMC and <b>Naka</b>
	Wafer Test	TeraPower	TeraPower and <b>Naka</b>
	Assembly	ATJ-Kumamoto	←
	Final Test, Visual Inspection and Packing	TeraPower, Tera Probe and Nishiki	←
Assembly	Assembly machines, materials and methods	No change	
Test	Tester, Test boards and Test Program	No change	
Packing materials		No change	

**Affected Product List:**

Please refer to “Product List” in “Appendix”.

**Reason for Change:**

For stable supply of products.

**Impact on Fit, Form, Function, Quality & Reliability:**

The change will have no impact on the form, fit, function, quality and reliability of the devices.

**Product Identification:**

Each product can be identified through Label and Mark. Please refer to page 4.

**Qualification Status:** Available from 11/15/2023

**Sample Availability Date:** N/A

**Device Material Declaration:** Please contact Renesas' sales representatives.

- Note:
1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the changes as approved.
  2. If timely acknowledgement is provided by customers, then customers shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If customers fail to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
  3. If customer cannot accept the PCN then customers must provide Renesas with the last order quantity and purchase order.

**For additional information regarding this notice, please contact your Renesas sales representative.**

## Appendix

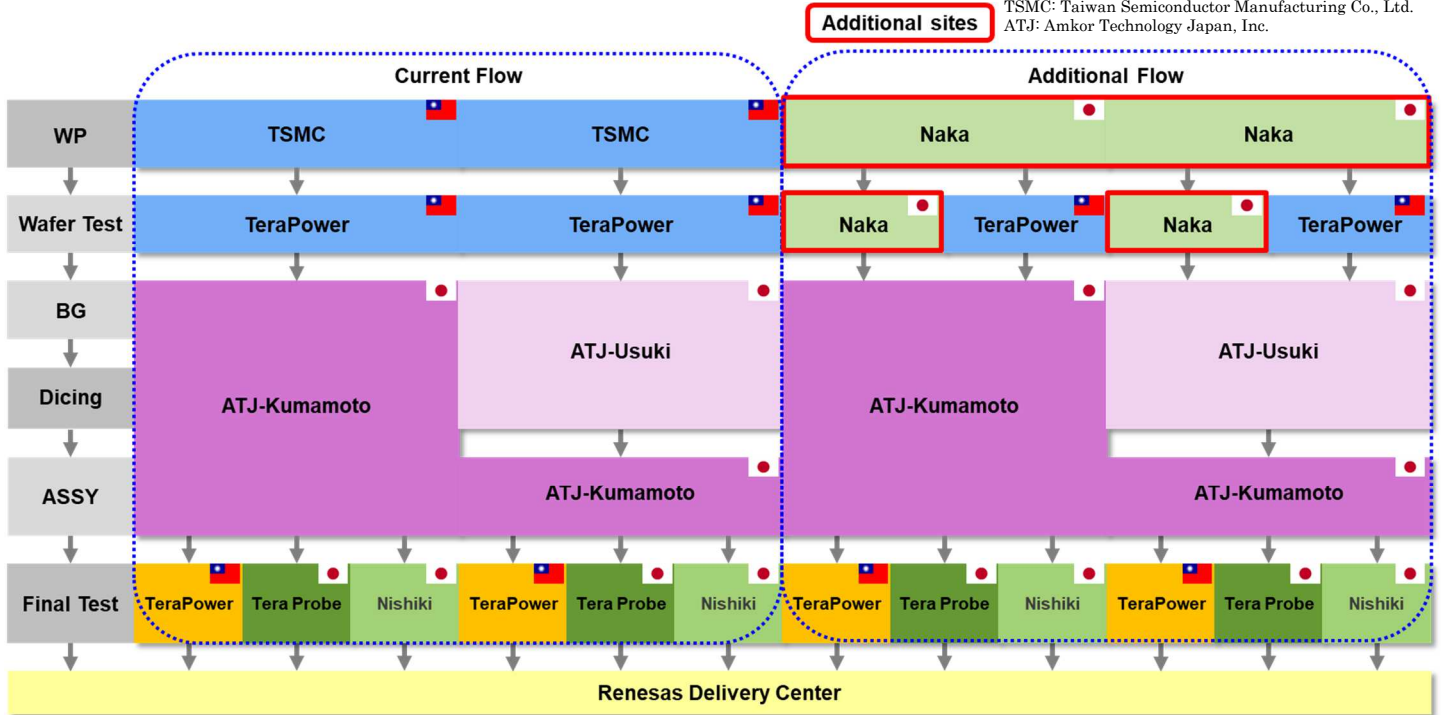
PCN#: [HDL2-0295]  
PC-MCU-A019B/E

## Product List

## RH850/F1L series

R7F7010063AFD-C#BA4	R7F7010343AFD-C#TA4	R7F7010534AFD-C#BA4	R7F7010224AFD-C#KA4
R7F7010063AFD-C#KA4	R7F7010344AFD-C#BA4	R7F7010534AFD-C#TA4	R7F7010233AFD-C#BA4
R7F7010064AFD-C#BA4	R7F7010344AFD-C#TA4	R7F7010543AFD-C#BA4	R7F7010233AFD-C#KA4
R7F7010064AFD-C#KA4	R7F7010463AFD-C#BA4	R7F7010543AFD-C#KA4	R7F7010234AFD-C#BA4
R7F7010073AFD-C#BA4	R7F7010463AFD-C#KA4	R7F7010544AFD-C#BA4	R7F7010234AFD-C#KA4
R7F7010073AFD-C#TA4	R7F7010464AFD-C#BA4	R7F7010544AFD-C#KA4	R7F701A323AFD-C#BA4
R7F7010074AFD-C#BA4	R7F7010464AFD-C#KA4	R7F7010553AFD-C#BA4	R7F701A323AFD-C#KA4
R7F7010074AFD-C#TA4	R7F7010473AFD-C#BA4	R7F7010553AFD-C#KA4	R7F701A324AFD-C#BA4
R7F7010263AFD-C#BA4	R7F7010473AFD-C#KA4	R7F7010554AFD-C#BA4	R7F701A324AFD-C#KA4
R7F7010263AFD-C#KA4	R7F7010474AFD-C#BA4	R7F7010554AFD-C#KA4	R7F701A333AFD-C#BA4
R7F7010264AFD-C#BA4	R7F7010474AFD-C#KA4	R7F7010563AFD-C#BA4	R7F701A333AFD-C#KA4
R7F7010264AFD-C#KA4	R7F7010483AFD-C#BA4	R7F7010563AFD-C#TA4	R7F701A334AFD-C#BA4
R7F7010273AFD-C#BA4	R7F7010483AFD-C#KA4	R7F7010564AFD-C#BA4	R7F701A334AFD-C#KA4
R7F7010273AFD-C#KA4	R7F7010484AFD-C#BA4	R7F7010564AFD-C#TA4	R7F701A363AFD-C#BA4
R7F7010274AFD-C#BA4	R7F7010484AFD-C#KA4	R7F7010573AFD-C#BA4	R7F701A363AFD-C#KA4
R7F7010274AFD-C#KA4	R7F7010493AFD-C#BA4	R7F7010573AFD-C#TA4	R7F701A364AFD-C#BA4
R7F7010283AFD-C#BA4	R7F7010493AFD-C#KA4	R7F7010574AFD-C#BA4	R7F701A364AFD-C#KA4
R7F7010283AFD-C#KA4	R7F7010494AFD-C#BA4	R7F7010574AFD-C#TA4	R7F7010033AFD-C#BA2
R7F7010284AFD-C#BA4	R7F7010494AFD-C#KA4	R7F701A003AFD-C#BA4	R7F7010033AFD-C#KA2
R7F7010284AFD-C#KA4	R7F7010503AFD-C#BA4	R7F701A003AFD-C#KA4	R7F7010034AFD-C#BA2
R7F7010293AFD-C#BA4	R7F7010503AFD-C#TA4	R7F701A004AFD-C#BA4	R7F7010034AFD-C#KA2
R7F7010293AFD-C#KA4	R7F7010504AFD-C#BA4	R7F701A004AFD-C#KA4	R7F7010243AFD-C#BA2
R7F7010294AFD-C#BA4	R7F7010504AFD-C#TA4	R7F701A013AFD-C#BA4	R7F7010243AFD-C#KA2
R7F7010294AFD-C#KA4	R7F7010513AFD-C#BA4	R7F701A013AFD-C#TA4	R7F7010244AFD-C#BA2
R7F7010303AFD-C#BA4	R7F7010513AFD-C#TA4	R7F701A014AFD-C#BA4	R7F7010244AFD-C#KA2
R7F7010303AFD-C#KA4	R7F7010514AFD-C#BA4	R7F701A014AFD-C#TA4	R7F7010253AFD-C#BA2
R7F7010304AFD-C#BA4	R7F7010514AFD-C#TA4	R7F7010023AFD-C#BA4	R7F7010253AFD-C#KA2
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R7F7010323AFD-C#BA4	R7F7010523AFD-C#BA8	R7F7010024AFD-C#BA4	R7F7010254AFD-C#KA2
R7F7010323AFD-C#TA4	R7F7010523AFD-C#TA4	R7F7010024AFD-C#KA4	R7F7010443AFD-C#BA2
R7F7010324AFD-C#BA4	R7F7010523AFD-C#TA8	R7F7010213AFD-C#BA4	R7F7010443AFD-C#KA2
R7F7010324AFD-C#TA4	R7F7010524AFD-C#BA4	R7F7010213AFD-C#KA4	R7F7010444AFD-C#BA2
R7F7010333AFD-C#BA4	R7F7010524AFD-C#TA4	R7F7010214AFD-C#BA4	R7F7010444AFD-C#KA2
R7F7010333AFD-C#TA4	R7F7010533AFD-C#BA4	R7F7010214AFD-C#KA4	R7F7010453AFD-C#BA2
R7F7010334AFD-C#BA4	R7F7010533AFD-C#BA8	R7F7010223AFD-C#BA4	R7F7010453AFD-C#KA2
R7F7010334AFD-C#TA4	R7F7010533AFD-C#TA4	R7F7010223AFD-C#KA4	R7F7010454AFD-C#BA2
R7F7010343AFD-C#BA4	R7F7010533AFD-C#TA8	R7F7010224AFD-C#BA4	R7F7010454AFD-C#KA2

WP: Wafer Process  
BG: Back Grinding process  
TSMC: Taiwan Semiconductor Manufacturing Co., Ltd.  
ATJ: Amkor Technology Japan, Inc.

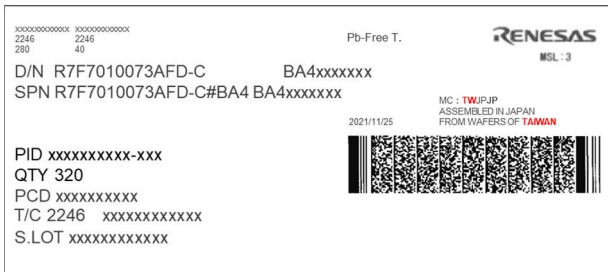


Production identification through label print:

Label Example: R7F7010073AFD-C#BA4 (F1L-2M, 176pin, Cu-wire)

The red characters are different.

TSMC Label Image



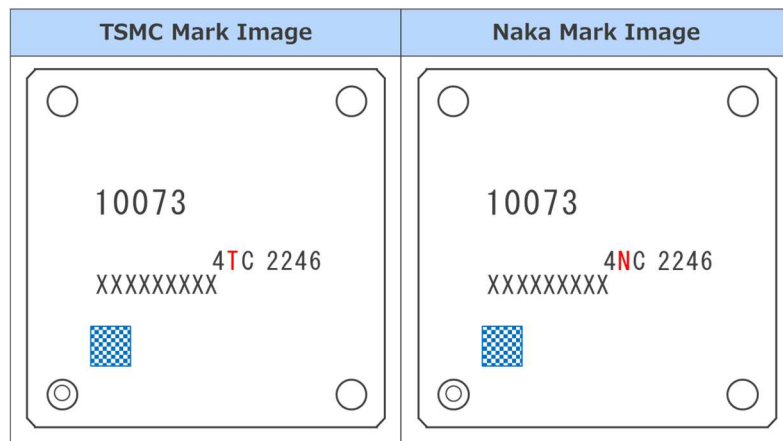
Naka Label Image



Production identification through Mark:

Label Example: R7F7010073AFD-C#BA4 (F1L-2M, 176pin, Cu-wire)

The red character is different.



■ : PKG-ID